EDCON COMPONENTS
A MEMBER OF EDCON-GROUP

DISCRIPTION

FEATURES

Ceramic Core
High frequency design
Excellent Q values
Excellent SRF
High reliability
Excellent thermal stability

OPTIONS

Tape & Reel is Standard (Qty: 3.000 Pcs)
Bulk Packing Available for smaller quantites
Tolerance: J = 5% and K=10% is Standard,
tighter Tolerance available (MOQ on request)

APPLICATIONS

Modems
Mobile Radios
Cordless Telephones
Global Positioning Systems
Telecommunications Systems

PHYSICAL CHARACTERISTICS

- Testing : (Equivalents acceptable) Inductance & Q-HP4191A + HP41951
  SRF : HP8753B ; RDC : 25°C
- Operating Temperature : Ceramic -55°C ~ 125°C
- Pad metalization : Tungsten-nickel with gold flash
- Solder methods : Wave, Reflow, Vapor Phase
- Solderability : Max 260°C for 10 seconds
- Marking : EIA color code

ELECTRICAL SPECIFICATIONS

Properties	Test conditions		Value	Unit	Tol.
Inductance		**L**	22	**nH**	**see Site 2**
Q factor		**Q**	55		**min.**
DC-resistance		**DCR typ.**	---	**Ω**	**typ.**
DC-resistance		**DCR max.**	0,220	**Ω**	**max.**
Self-Res. Freq.		**SRF**	2600	**Mhz**	**min.**
Test-Freq.			500	**Mhz**	
Rated Current		**IDC**	500	**mA**	**max.**
Saturation Current		**Isat**	---	**mA**	**typ.**

1. This electronic component is meant to be used in general electronic equipment. Before the incorporation of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical, public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon –Components must be informed before the stage of design-in. Evaluation checks for safety have to be performed on each electronic components used in electrical circuits that require high safety and reliability functions.

SMT WIRE-WOUND CERAMIC CHIP INDUCTORS

Part No.: **S12003-22N**

Customer:

DRW:	Chang	CHKD	Young	MATL:	Chu Chi	DATE	09.06.2009
APPD:	Pong			FINISH	Vienna	Sheet	1 from 2

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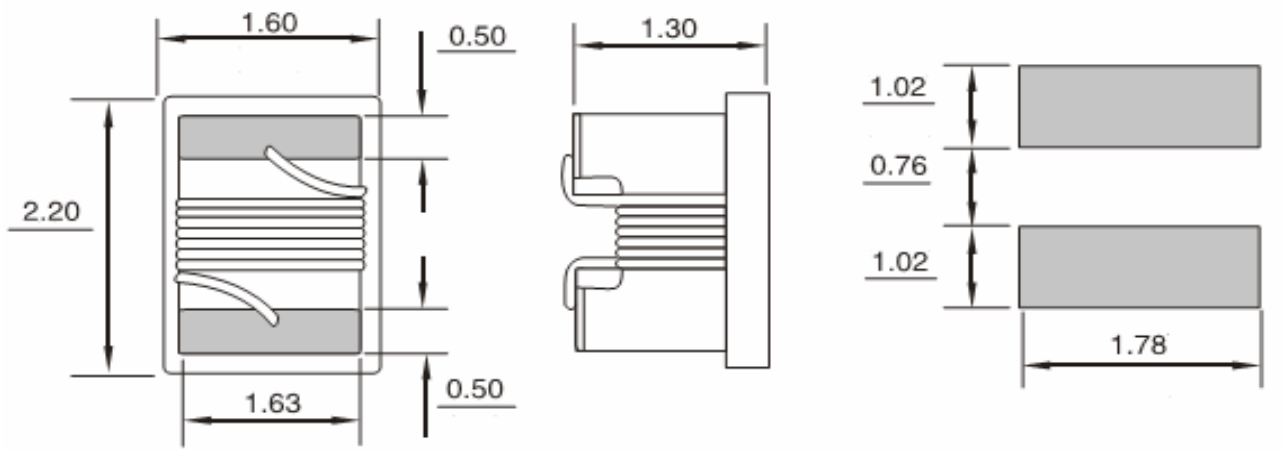
TECHNICAL INFORMATIONS

Dimensions (mm)

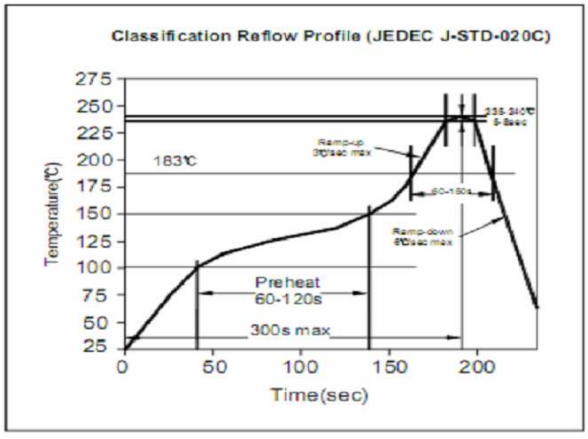


Ordering Information

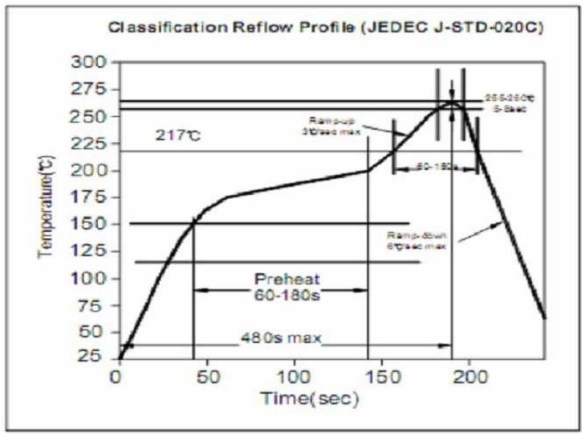
Serie and Range	Tolerance	ROHS	Packing
S12003-22N	K	R	TR

J = 5%	**R =** ROHS	**BU =** Bulk Ware
K = 10%	**N =** non ROHS	**TR =** Tape Reel
M = 20%		
N = 30%		

Soldering Profile for Lead Free Soldering 235-240°C



Soldering Profile for Lead Free Soldering 255-260°C



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